

Chemicals contained in products

Package-type

Epson Package name; **TQFP15-128PIN / Halogen free**

JEITA Package name; **P-TQFP128-1414-0.40**

Lead frame plating; **Lead(Pb) Free**

Weight; **0.52 [g]** *Note1

Part	Subpart	Subpart weight [mg]	Substance name	CAS No.	Content *Note2		Application
					[mg]	[ppm]	
IC Die	IC Die	5.9	Silicon	7440-21-3	5.9	999894	Base material
			Boron	7440-42-8	0.00001	2	Dopant
			Phosphorus	7723-14-0	0.00003	5	Dopant
			Aluminum	7429-90-5	0.0001	20	Metalization
			Arsenic *Note3	7440-38-2	0.00003	5	Dopant
			Fluorine *Note3	7782-41-4	0.00001	2	Dopant
			Titanium *Note3	7440-32-6	0.0001	20	Metalization
			Molybdenum *Note3	7439-98-7	0.0001	20	Metalization
			Tungsten *Note3	7440-33-7	0.0002	30	Metalization
			Cobalt *Note3	7440-48-4	0.00001	2	Metalization
	Stress buffer coat	0.12	Polyimide	-	0.12	1000000	Stress buffer coat *Note4
Package	Die Bonding material	1.43	Silver	7440-22-4	0.92	640000	Base material
			Epoxy resin	-	0.29	205000	Adhesive
			Phenol resin	-	0.11	80000	Adhesive
			Inorganic powder	-	0.07	48000	Additive
			Bismuth compound	-	0.04	27000	Ion trap
	Lead Frame Plating	12.20	Tin	7440-31-5	12.20	1000000	Solder
	Lead Frame	156.78	Copper	7440-50-8	148.20	945000	Conductor
			Silver	7440-22-4	0.78	5000	Inner lead plating
			Others *Note5	-	7.80	50000	Additive
	Bonding Wire	2.90	Gold	7440-57-5	2.90	1000000	Conductor
	Mold resin	340.70	Epoxy resin	-	17.00	50000	Base material
			Silica	60676-86-0/-	308.40	905000	Filler
			Carbon black	1333-86-4	1.70	5000	Coloring agent
			Hardening chemical(ex:Phenol resin)	-	13.60	40000	Base material

Regarding the information of chemical substances

*Note1 The weight might be somewhat different depending on an individual built-in IC-chip specification like the size etc.

*Note2 Content data are estimated values based on supplier information and intended levels of content in product.

Actual measurements may vary from these values somewhat.

*Note3 Use or not-use of these substances depends on individual built-in IC-chip specification.

*Note4 The stress buffer coat may not be used depending on the individual model.

*Note5 The nickel, zinc, tin, silicon, iron, and the zinc oxide are included.